ł

04-26-2006

RE(

To th	e Director, U.S. Patent and Tradema	ginal documents or copy thereof.				
90.5/-h	Name of conveying party(ies): (List using letters or numbers for multiple parties) 1. Hyun-Soo Shin 2. Jae-Bon Koo 3. Yeon-Gon Mo 4. Jae-Kyeong Jeong dditional name(s) of conveying party(ies) tached? () Yes (X) No	2260111 2. Name: Samsung SDI Co., Ltd. Internal Address: 575 Shin-dong, Yeongtong-gu Suwon-si Street Address: 575 Shin-dong, Yeongtong-gu, 5000000000000000000000000000000000000				
	signatures) 1. March 27, 2006 2. March 27, 2006 3. March 27, 2006 4. March 27, 2006	 (X) Application(s) filed herewith Additional numbers attached? () Yes (X) No 				
A	Party to whom correspondence concerning document should be mailed: ustomer No. 20,995 ddress: Knobbe, Martens, Olson & Bear, LLP 2040 Main Street, 14 th Floor Irvine, CA 92614 eturn Fax: (949) 760-9502 ttorney's Docket No.: SDIYPL.037AUS	 Total number of applications and patents involved: 1 				
	Total fee (37 CFR 1.21(h)): \$40	 Deposit account number: 11-1410 Please charge this account for any additional fees which may be required, or credit any overpayment to this account. 				
9	To the best of my knowledge and belief, the foregoin is a true copy of the original document. John M. Carson	ing information is true and correct, and any attached copy $\frac{4/19/06}{Date}$				
Total number of pages including cover sheet, attachments and document: 3						
Docu	ments transmitted via Mail to be recorded with require	d cover sheet information to:				
04 FC:80	21 40.00 OP Director, U.S. Patent P.O. B	t Recordation Services and Trademark Office ox 1450 A 22313-1450				

PATENT REEL: 017809 FRAME: 0794

ASSIGNMENT

WHEREAS, we, the undersigned, have invented certain new and useful improvements in a FLAT PANEL DISPLAY AND METHOD OF MANUFACTURING THE SAME, the specification of which was executed on even date herewith.

AND WHEREAS, Samsung SDI Co., Ltd., (hereinafter "ASSIGNEE"), with its principal place of business at 575 Shin-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea, desires to acquire the entire right, title, and interest in and to the said improvements with respect to the United States of America, its territories and possessions.

NOW, THEREFORE, in light of good and valuable consideration, the receipt of which is hereby acknowledged, we, the said inventors, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all provisional applications relating thereto, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States and all Letters Patent which may be granted thereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

Date: 27 March 2006

11.1

Simpture	1 dyumsoo Arin
Signature	- 0

Name: Hyun-Soo Shin

Address :	c/o Samsung SDI Co., Ltd.
-----------	---------------------------

575 Shin-dong, Yeongtong-gu, Suwon-si,

Gveonggi-do, Republic of Korea

Application No.: Unknown Filing Date: Herewith PATENT Client Code: SDIYPL.037AUS Page 2

Date:	27	March	2006	Signature: Jal Bor Ka
				Name: Jae-Bon Koo
				Address : <u>c/o Samsung SDI Co., Ltd.</u>
				575 Shin-dong, Ycongtong-gu, Suwon-si,
				Gyeonggi-do, Republic of Korea
_	27	Nowek	2006	And Ch
Date:		March	2006	Signature
-				Name: Yeon-Gon Mo
				Address : <u>c/o Samsung SDI Co., Ltd.</u>
				575 Shin-dong, Yeongtong-gu, Suwon-si,
				Gyeonggi-do, Republic of Korea
Date:	27	March	2006	Signature: M/Q
				Name: Jae-Kyeong Jeong
				Address : c/o Samsung SDI Co., Ltd.
				575 Shin-dong, Yeongtong-gu, Suwon-si,
				Gyeonggi-do, Republic of Koree

.

1944130-gem092105

RECORDED: 04/19/2006